'46A, '47A, 'LS47 feature

- Open-Collector Outputs
 Drive Indicators Directly
- Lamp-Test Provision
- Leading/Trailing Zero Suppression

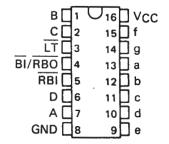
'48, 'LS48 feature

- Internal Pull-Ups Eliminate
 Need for External Resistors
- Lamp-Test Provision
- Leading/Trailing Zero Suppression

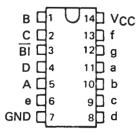
'LS49 feature

- Open-Collector Outputs
- Blanking Input

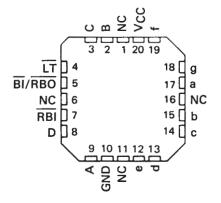
SN5446A, SN5447A, SN54LS47, SN5448, SN54LS48 . . . J PACKAGE SN7446A, SN7447A, SN7448 . . . N PACKAGE SN74LS47, SN74LS48 . . . D OR N PACKAGE (TOP VIEW)



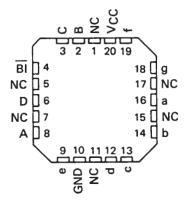
SN54LS49 . . . J OR W PACKAGE SN74LS49 . . . D OR N PACKAGE (TOP VIEW)



SN54LS47, SN54LS48 . . . FK PACKAGE (TOP VIEW)



SN54LS49 . . . FK PACKAGE (TOP VIEW)

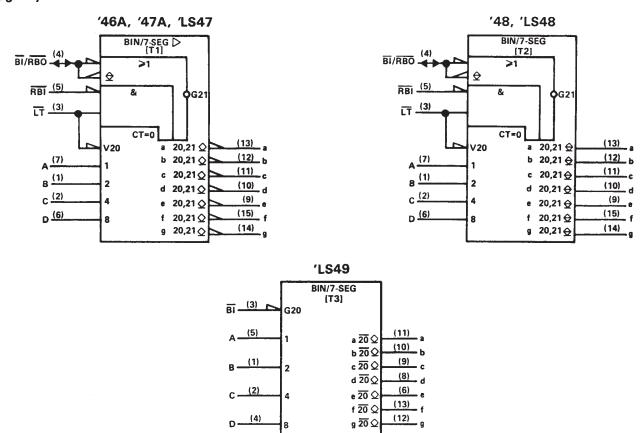


NC - No internal connection

All Circuit Types Feature Lamp Intensity Modulation Capability

		DRIVER O	UTPUTS		TYPICAL	
TYPE	ACTIVE	OUTPUT	SINK	MAX	POWER	PACKAGES
	LEVEL	CONFIGURATION	CURRENT	VOLTAGE	DISSIPATION	
SN5446A	low	open-collector	40 mA	30 V	320 mW	J, W
SN5447A	low	open-collector	40 mA	15 V	320 mW	J, W
SN5448	high	2-kΩ pull-up	6.4 mA	5.5 V	265 mW	J,W
SN54LS47	low	open-collector	12 mA	15 V	35 mW	J, W
SN54LS48	high	2-kΩ pull-up	2 mA	5.5 V	125 mW	J, W
SN54LS49	high	open-collector	4 mA	5.5 V	40 mW	J, W
SN7446A	low	open-collector	40 mA	30 V	320 mW	J, N
SN7447A	low	open-collector	40 mA	15 V	320 mW	J, N
SN7448	high	2-kΩ pull-up	6.4 mA	5.5 V	265 mW	J, N
SN74LS47	low	open-collector	24 mA	15 V	35 mW	J, N
SN74LS48	high	2-kΩ pull-up	6 mA	5.5 V	125 mW	J, N
SN74LS49	high	open-collector	8 mA	5.5 V	40 mW	J, N

logic symbols†



[†]These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for D, J, N, and W packages.

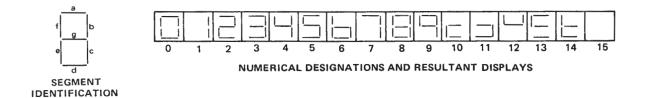


description

The '46A, '47A, and 'LS47 feature active-low outputs designed for driving common-anode LEDs or incandescent indicators directly. The '48, 'LS48, and 'LS49 feature active-high outputs for driving lamp buffers or common-cathode LEDs. All of the circuits except 'LS49 have full ripple-blanking input/output controls and a lamp test input. The 'LS49 circuit incorporates a direct blanking input. Segment identification and resultant displays are shown below. Display patterns for BCD input counts above 9 are unique symbols to authenticate input conditions.

The '46A, '47A, '48, 'LS47, and 'LS48 circuits incorporate automatic leading and/or trailing-edge zero-blanking control $(\overline{RBI} \text{ and } \overline{RBO})$. Lamp test (\overline{LT}) of these types may be performed at any time when the $\overline{BI/RBO}$ node is at a high level. All types (including the '49 and 'LS49) contain an overriding blanking input (BI), which can be used to control the lamp intensity by pulsing or to inhibit the outputs. Inputs and outputs are entirely compatible for use with TTL logic outputs.

The SN54246/SN74246 and '247 and the SN54LS247/SN74LS247 and 'LS248 compose the $\,\Box\,$ and the $\,\Box\,$ with tails and were designed to offer the designer a choice between two indicator fonts.



'46A, '47A, 'LS47 FUNCTION TABLE (T1)

DECIMAL OR			INP	JTS			BI/RBO†			0	UTPUT	s			NOTE
FUNCTION	LT	RBI	D	С	В	Α		а	ь	С	d	е	f	g	
0	Н	Н	L.	L	L	L	Н	ON	ON	ON	ON	ON	ON	OFF	
1	н	×	L	L	L	Н	н	OFF	ON	ON	OFF	OFF	OFF	OFF	
2	н	x	L	L	Н	L	н	ON	ON	OFF	ON	ON	OFF	ON	
3	Н	×	L	L	Н	Н	н	ON	ON	ON	ON	OFF	OFF	ON	
4	Н	×	L	Н	L	L	Н	OFF	ON	ON	OFF	OFF	ON	ON	
5	н	x	L	Н	L	Н	н	ON	OFF	ON	ON	OFF	ON	ON	
6	н	×	L	Н	Н	Ĺ	н	OFF	OFF	ON	ON	ON	ON	ON	
7	н	x	L	Н	Н	н	н	ON	ON	ON	OFF	OFF	OFF	OFF	1
8	Н	×	н	L	L	L	н	ON	ON	ON	ON	ON	ON	ON	' '
9	н	x	н	L	L	н	н	ON	ON	ON	OFF	OFF	ON	ON	
10	н	X	н	L	Н	L	H	OFF	OFF	OFF	ON	ON	OFF	ON	i
11	Н	X	Н	L	н	Н	н	OFF	OFF	ON	ON	OFF	OFF	ON	
12	Н	×	н	Н	L	L	н	OFF	ON	OFF	OFF	OFF	ON	ON	
13	н	X	н	н	L	Н	н	ON	OFF	OFF	ON	OFF	ON	ON	
14	н	X	н	Н	н	L	н	OFF	OFF	OFF	ON	ON	ON	ON	
15	н	X	Н	н	Н	Н	н	OFF	OFF	OFF	OFF	OFF	OFF	OFF	
81	Х	Х	Х	Х	Х	Х	L	OFF	OFF	OFF	OFF	OFF	OFF	OFF	2
RBI	н	L	L	L	L	L	L	OFF	OFF	OFF	OFF	OFF	OFF	OFF	3
LT	L	X	X	X	Х	Х	н	ON	ON	ON	ON	ON	ON	ON	4

H = high level, L = low level, X = irrelevant

NOTES: 1. The blanking input (BI) must be open or held at a high logic level when output functions 0 through 15 are desired. The ripple-blanking input (RBI) must be open or high if blanking of a decimal zero is not desired.

- 2. When a low logic level is applied directly to the blanking input (BI), all segment outputs are off regardless of the level of any
- 3. When ripple-blanking input (RBI) and inputs A, B, C, and D are at a low level with the lamp test input high, all segment outputs go off and the ripple-blanking output ($\overline{\mathsf{RBO}}$) goes to a low level (response condition).
- 4. When the blanking input/ripple blanking output (BI/RBO) is open or held high and a low is applied to the lamp-test input, all segment outputs are on.

¹BI/RBO is wire AND logic serving as blanking input (BI) and/or ripple-blanking output (RBO).



'48, 'LS48 FUNCTION TABLE (T2)

DECIMAL OR		INPUTS		BI/RBO†			οι	JTPU	TS			NOTE			
FUNCTION	LT	RBI	D	С	В	Α		а	b	c _	d	е	f	g	
0	Н	Н	L	L	L.	L	Н	Н	Н	Н	Н	Н	Н	L	
1	Н	x	L	L	L	н	н	L	Н	Н	L	L	L	니	
2	н	x	L	L	Н	L	Н	Н	Н	L	Н	Н	L	H	
3	н	Х	L	L	H	Н	Н	Н	<u>H</u>	Н	Н	L	L	Н	
4	Н	X	L	Н	L	L	Н	L	Н	Н	L	L	Н	н	
5	н	х	L	Н	L	Н	н	н	L	Н	Н	L	Н	н	
6	н	X	L	Н	Н	L	H	L	L	Н	н	Н	Н	н	
7	н	Х	L	Н	Н	H	Н	Н	Н	_H	L	L	L	L	1
8	Н	Х	Н	L	L	L	Н	Н	Н	Н	Н	Н	Н	Н	•
9	Н '	×	Н	L	L	Н	Н	н	Н	Н	L	L	Н	Н	
10	Н	x	Н	L	Н	L	н	L	L	L	Н	Н	L	Н	
11	Н	Х	Н	L	Н	Н	H	L	L.	H	<u>H</u>	L	L	Н	
12	Н	Х	Н	Н	L	L	Н	L	Н	L	L	L	Н	Н	
13	н	×	н	н	L	Н	н	Н	L	L	Н	L	Н	Н	
14	Н	×	н	Н	Н	L	н	L	L	L	Н	Н	Н	Н	
15	Н	×	Н	Н	Н	Н	Н	L.	L	L	L	L	L	L	
BI	X	×	Х	X	Х	Х	L	L	L	L	L	L	L	L	2
RBI	н	L	L	L	L	L	L	L	L	L	L	L	L	L	3
LT	L	×	Х	X	Х	X	Н	Н	Н	Н	H	Н	H	Н	4

H = high level, L = low level, X = irrelevant

NOTES: 1. The blanking input (BI) must be open or held at a high logic level when output functions 0 through 15 are desired. The ripple-blanking input (RBI) must be open or high, if blanking of a decimal zero is not desired.

- 2. When a low logic level is applied directly to the blanking input (BI), all segment outputs are low regardless of the level of any other input.
- 3. When ripple-blanking input (RBI) and inputs A, B, C, and D are at a low level with the lamp-test input high, all segment outputs go low and the ripple-blanking output (RBO) goes to a low level (response condition).
- 4. When the blanking input/ripple-blanking output (BI/RBO) is open or held high and a low is applied to the lamp-test input, all segment outputs are high.

tBI/RBO is wire-AND logic serving as blanking input (\overline{BI}) and/or ripple-blanking output (\overline{RBO}).

'LS49 FUNCTION TABLE (T3)

DECIMAL OR		II	IPUT	s				οι	JTPU	тѕ			NOTE
FUNCTION	D	С	В	Α	BI	а	b	С	d	е	f	g	
0	L	L	L	L	Н	Н	Н	Н	Н	Н	Н	L	
1	L	L	L	Н	н	L	Н	Н	L	L	L	L	
2	L	L	Н	L	Н	н	Н	L	Н	Н	L	Н	
3	L	L	Н	H	Н	Н	Н	Н	H	L	L	H	
4	L	Н	L	L	Н	L	Н	Н	L	L	Н	Н	
5	L	H	L	Н	Н	н	L	Н	Н	L	Н	Н	
6	L	Н	Н	L	Н	L	L	Н	Н	Н	Н	Н	
7	L	Н	H	Н	H	Н	Н	Н	L	L	L	L	1
8	Н	L	L	L	Н	Н	Н	Н	Н	Н	Н	Н	`
9	Н	L	L	Н	Н	н	Н	Н	L	L	Н	Н	
10	Н	L	Н	L	Н	L	L	L	Н	Н	L	Н	
11	н	L	Н	Н	H	L	L	H	Н	L	L	Н	
12	Н	Н	L	L	Н	L	Н	L	L	L	Н	Н	
13	Н	Н	L	Н	H	Н	L	L	Н	L	Н	Н	
14	н	Н	Н	L	Н	L	L	L	Н	Н	Н	Н	
15	l H	Н	Н	Н	Н	L_	L	L	L	L	L	L	
BI	X	X	×	Х	L	L	L	L	L	L	L	L	2

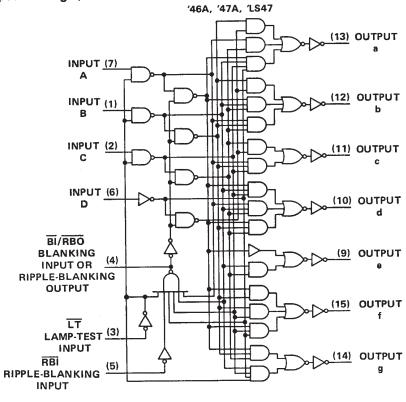
H = high level, L = low level, X = irrelevant

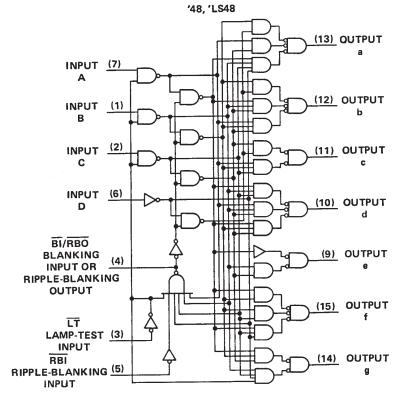
NOTES: 1. The blanking input (BI) must be open or held at a high logic level when output functions 0 through 15 are desired.

 When a low logic level is applied directly to the blanking input (BI), all segment outputs are low regardless of the level of any other input.



logic diagrams (positive logic)

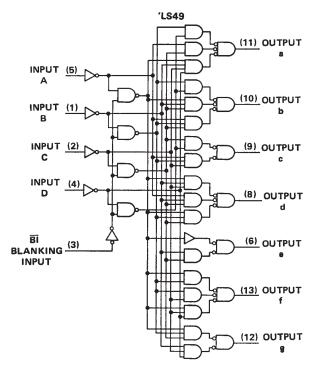




Pin numbers shown are for D, J, N, and W packages.



logic diagrams (continued)

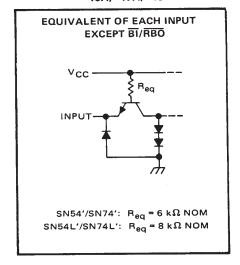


Pin numbers shown are for D, J, N, and W packages.

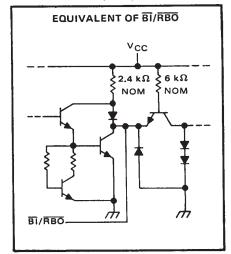


schematics of inputs and outputs

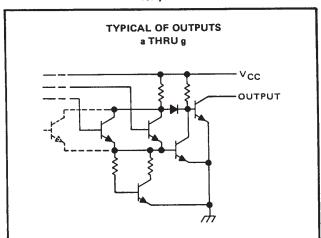
'46A, '47A, '48



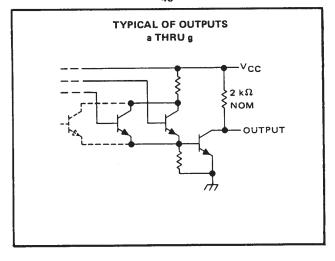
'46A, '47A, '48



'46A, '47A

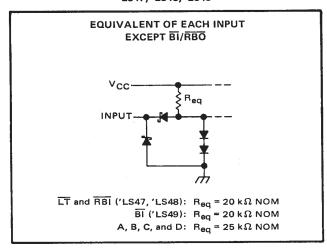


'48

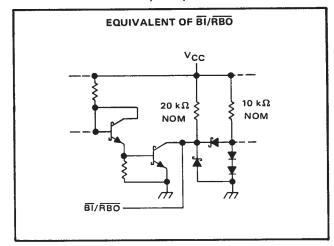


schematics of inputs and outputs

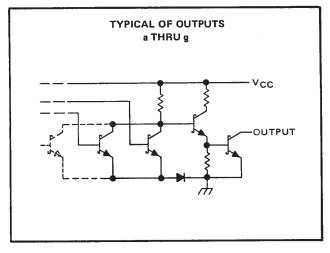
'LS47, 'LS48, 'LS49

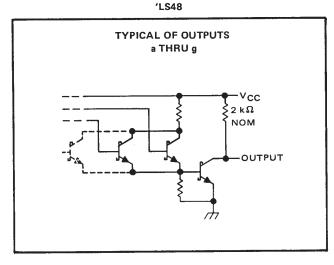


'LS47, 'LS48, 'LS49

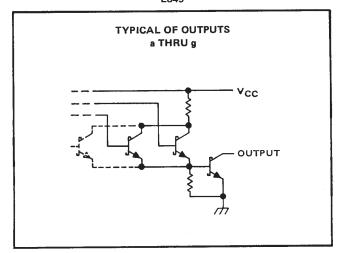


'LS47





'LS49





absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1) .																				7 V
Input voltage																				5.5 V
Current forced into any output in the	off	state	е																	1 mA
Operating free-air temperature range:	SN	5446	ŝΑ,	Si	V54	44	7A									-!	55°	,C	to	125°C
	SN	7446	δA,	Si	٧7	44	7A										(o°(C to	o 70°C
Storage temperature range																				

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

		5	N5446	Α		N5447	A	5	N7446	A	5	UNIT		
		MIN	NOM	MAX	MIN	NOM	MAX	MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Supply voltage, V _{CC}		4.5	5	5.5	4.5	5	5.5	4.75	5	5.25	4.75	5	5.25	V
Off-state output voltage, VO(off)	a thru g			30			15			30			15	٧
On-state output current, IO(on)	a thru g			40			40			40			40	mA
High-level output current, IOH	BI/RBO			-200			-200			-200			-200	μА
Low-level output current, IOL	BI/RBO			8			8			8			8	mA
Operating free-air temperature, TA	Α	-55	-	125	-55		125	0	2	70	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER		TEST CONDIT	IONS [†]	MIN	TYP‡	MAX	UNIT
VIH	High-level input voltage				2			V
VIL	Low-level input voltage						0.8	V
VIK	Input clamp voltage		VCC = MIN, II =	-12 mA			-1.5	V
VOH	High-level output voltage	BI/RBO	V _{CC} = MIN, V _{IH} V _{IL} = 0.8 V, I _{OH}		2.4	3.7		V
V _{OL}	Low-level output voltage	BI/RBO	V _{CC} = MIN, V _{IH} V _{IL} = 0.8 V, I _{OL}	1		0.27	0.4	٧
IO(off)	Off-state output current	a thru g	V _{CC} = MAX, V _{IH} V _{IL} = 0.8 V, V _O (250	μА
V _{O(on)}	On-state output voltage	a thru g	V _{CC} = MIN, V _{IH} V _{IL} = 0.8 V, I _O (c			0.3	0.4	٧
l _l	Input current at maximum input voltage	Any input except BI/RBO	VCC = MAX, Vi =	5.5 V			1	mA
ЧН	High-level input current	Any input except BI/RBO	VCC = MAX, VI =	2.4 V			40	μА
IIL	Low-level input current	Any input except BI/RBO	V _{CC} = MAX, V _I =	0.4 V			-1.6	mA
		BI/RBO					-4	
los	Short-circuit output current	BI/RBO	V _{CC} = MAX				-4	mA
Icc	Supply current		V _{CC} = MAX, See Note 2	SN54' SN74'		64 64	85 103	mA

[†]For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics, VCC = 5 V, TA = 25°C

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
toff	Turn-off time from A input				100	ns
ton	Turn-on time from A input	$C_L = 15 pF$, $R_L = 120 \Omega$,			100] ""
toff	Turn-off time from RBI input	See Note 3			100	ns
ton	Turn-on time from RBI input				100] '''

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



 $[\]ddagger$ All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

NOTE 2: ICC is measured with all outputs open and all inputs at 4.5 V.

SN5446A, '47A, '48, SN54LS47, 'LS48, 'LS49 SN7446A, '47A, '48, SN74LS47, 'LS48, 'LS49 **BCD-TO-SEVEN-SEGMENT DECODERS/DRIVERS**

SDLS111 - MARCH 1974 - REVISED MARCH 1988

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

V
V
°C
°C
°C
)

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

			SN544	В		8	UNIT	
		MIN	NOM	MAX	MIN	NOM	MAX	OIVIT
Supply voltage, V _{CC}		4.5	5	5.5	4.75	5	5.25	V
	a thru g			-400			-400	μА
High-level output current, IOH	BI/RBO			-200			200	μΑ
	a thru g			6.4			6.4	mA
Low-level output current, IOL	BI/RBO			8			8	IIIA
Operating free-air temperature, TA		-55		125	0		70	°c

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER		TEST CONI	OITIONS†	MIN	TYP‡	MAX	UNIT
VIH	High-level input voltage				2			V
VIL	Low-level input voltage						0.8	V
VIK	Input clamp voltage		V _{CC} = MIN, II	= -12 mA			-1.5	V
Voн	High-level output voltage	a thru g	V _{CC} = MIN, V V _{II} = 0.8 V, I _C		2.4	3.7		V
10	Output current	a thru g	V _{CC} = MIN, V	O = 0.85 V,	-1.3	-2		mA
VOL	Low-level output voltage		V _{CC} = MIN, V V _{IL} = 0.8 V, I _C			0.27	0.4	٧
Ц	Input current at maximum input voltage	Any input except BI/RBO	V _{CC} = MAX, V	₁ = 5.5 V			1	mA
ΙΗ	High-level input current	Any input except BI/RBO	V _{CC} = MAX, V	= 2.4 V			40	μА
IIL	Low-level input current	Any input except BI/RBO BI/RBO	V _{CC} = MAX, V	' _I = 0.4 V			-1.6 -4	mA
los	Short-circuit output current	BI/RBO	V _{CC} = MAX				-4	mA
Icc	Supply current		V _{CC} = MAX, See Note 2	SN5448 SN7448		53 53	76 90	-l mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTE 2: ICC is measured with all outputs open and all inputs at 4.5 V.

switching characteristics, VCC = 5 V, TA = 25 °C

PARAMETER	TEST CONDITIONS	MIN TYP	MAX	UNIT
[†] PHL Propagation delay time, high-to-low-level output from A input			100	ns
tpLH Propagation delay time, low-to-high-level output from A input	$C_L = 15 \text{ pF}, R_L = 1 \text{ k}\Omega$		100	113
tpHL Propagation delay time, high-to-low-level output from RBI input	See Note 3		100	ns
[†] PLH Propagation delay time, low-to-high-level output from RBI input			100	

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



 $[\]ddagger$ AII typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25 ^{\circ}\text{C}$.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)	7 V
Input voltage	
Peak output current ($t_W \le 1$ ms, duty cycle $\le 10\%$)	mΑ
Current forced into any output in the off state	mΑ
Operating free-air temperature range: SN54LS47	25°C
SN74LS47	O°C
Storage temperature range	o°C

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

		S	N54LS4	17	S	N74LS4	17	
		MIN	NOM	MAX	MIN	NOM	MAX	TINU
Supply voltage, V _{CC}		4.5	5	5.5	4.75	5	5.25	V
Off-state output voltage, VO(off)	a thru g		***	15			15	V
On-state output current, IO(on)	a thru g			12			24	mA
High-level output current, IOH	BI/RBO			-50			-50	μА
Low-level output current, IOL	BI/RBO			1.6			3.2	mA
Operating free-air temperature, TA		-55		125	0		70	°c

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER		TEST COM	IDITIONS†	S	N54LS4	17	S	N74LS	47	
	FARAMETER		1EST CON	DITIONS.	MIN	TYP [‡]	MAX	MIN	TYP [‡]	MAX	UNIT
VIH	High-level input voltage				2			2			V
VIL	Low-level input voltage						0.7			0.8	V
VIK	Input clamp voltage		V _{CC} = MIN,	I ₁ = -18 mA			-1.5			-1.5	V
v _{OH}	High-level output voltage	BI/RBO	V _{CC} = MIN, V _{IL} = V _{IL} max,	V _{IH} = 2 V, I _{OH} = -50 μA	2.4	4.2		2.4	4.2		V
VOL	Low-level output voltage	BI/RBO	V _{CC} = MIN, V _{IH} = 2 V,	I _{OL} = 1.6 mA		0.25	0.4		0.25	0.4	v
			VIL = VIL max	I _{OL} = 3.2 mA					0.35	0.5	
IO(off)	Off-state output current	a thru g	V _{CC} = MAX, V _{IL} = V _{IL} max,	V _{IH} = 2 V, V _{O(off)} = 15 V			250			250	μА
V _{O(on)}	On-state output voltage	a thru q	V _{CC} = MIN, V _{IH} = 2 V,	l _{O(on)} = 12 mA		0.25	0.4		0.25	0.4	v
0 (011)			V _{IL} = V _{IL} max	1 _{O(on)} = 24 mA					0.35	0.5	
I _I	Input current at maximur	n input voltage	V _{CC} = MAX,	V _I = 7 V			0.1			0.1	mA
IJН	High-level input current		V _{CC} = MAX,	V _I = 2.7 V			20			20	μА
I _I L	Low-level input current	Any input except BI/RBO	V _{CC} = MAX,	V _I = 0.4 V			-0.4			-0.4	mA
		BI/RBO					-1.2			-1.2	
Ios	Short-circuit output current	BI/RBO	V _{CC} = MAX		-0.3		-2	-0.3		-2	mA
1cc	Supply current		V _{CC} = MAX,	See Note 2		7	13		7	13	mA

[†]For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡All typical values are at V_{CC} = 5 V, T_A = 25°C. NOTE 2: I_{CC} is measured with all outputs open and all inputs at 4.5 V.

switching characteristics, VCC = 5 V, TA = 25 °C

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
toff	Turn-off time from A input				100	
ton	Turn-on time from A input	$C_L = 15 \text{ pF}, R_L = 665 \Omega,$			100	ns
toff	Turn-off time from RBI input, outputs (a-f) only	See Note 3			100	
ton	Turn-on time from RBI input, outputs (a-f) only				100	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



SN5446A, '47A, '48, SN54LS47, 'LS48, 'LS49 SN7446A, '47A, '48, SN74LS47, 'LS48, 'LS49 **BCD-TO-SEVEN-SEGMENT DECODERS/DRIVERS**

SDLS111 - MARCH 1974 - REVISED MARCH 1988

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1) .													 							7	V
Input voltage					_	_	_	_			_			 							7	V
Operating free-air temperature ra	inge:	SN	54L	.S4	8									 					55°	C to	125°	С
		SN	74 L	_S4	8								•			•			U	Ut	0 /U	C
Storage temperature range												•	•	 		•	•	-6	35°	C to	150°	С

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

		s	N54LS4	18	S	N74LS4	18	UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	OWIT
Supply voltage, VCC		4.5	5	5.5	4.75	5	5.25	٧
	a thru g			-100			-100	μА
High-level output current, IOH	BI/RBO	1		-50			-50	μΑ.
	a thru g			2			6	mA
Low-level output current, IOL	BĪ/RBO			1.6			3.2	IIIA
Operating free-air temperature, TA		-55		125	0		70	°c

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	0.		TEST CON	DITIONS	S	N54LS4	18	S	N74LS4	8	UNIT
	PARAMETER		TEST CON	י פאטווות.	MIN	TYP‡	MAX	MIN	TYP [‡]	MAX	Olvii
VIH	High-level input voltage	-			2			2			V
VIL	Low-level input voltage						0.7			0.8	V
VIK	Input clamp voltage		V _{CC} = MIN,	l ₁ = -18 mA			-1.5			-1.5	V
Voн	High-level output voltage	a thru g and BI/RBO	V _{CC} = MIN, V _{IL} = V _{IL} max,	V _{IH} = 2 V, I _{OH} = MAX	2.4	4.2		2.4	4.2		v
I _O	Output current	a thru g	V _{CC} = MIN, Input conditions	$V_O = 0.85 V$, as for V_{OH}	-1.3	-2		-1.3	-2		mA
		a thru a	V _{CC} = MIN,	I _{OL} = 2 mA		0.25	0.4		0.25	0.4	V
\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	Low-level output voltage	a thru g	V _{IH} = 2 V, V _{IL} = V _{IL} max	IOL = 6 mA					0.35	0.5	
VOL	LOW-level output voltage	BI/RBO	V _{CC} = MIN, V _{IH} = 2 V,	I _{OL} = 1.6 mA		0.25	0.4		0.25	0.4	l ,
		ВІ/КВО	VIH = VIL max	I _{OL} = 3.2 mA					0.35	0.5	1 - 1
11	Input current at maximum input voltage	Any input except BI/BRO	V _{CC} = MAX,	V ₁ = 7 V			0.1			0.1	mA
ΊΗ	High-level input current	Any input except BI/RBO	V _{CC} = MAX,	V _I = 2.7 V			20			20	μΑ
111	Low-level input current	Any input except BI/RBO	V _{CC} = MAX,	V _I = 0.4 V			-0.4			-0.4	mA
		BI/RBO					-1.2			-1.2	<u> </u>
los	Short-circuit output current	BI/RBO	V _{CC} = MAX		-0.3		-2	-0.3		-2	mA
¹cc	Supply current		V _{CC} = MAX,	See Note 2		25	38		25	38	mA

[†]For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25 \, ^{\circ}\text{C}$

PARAMETER	TEST CONDITIONS	MIN TY	P MAX	UNIT
tPHL Propagation delay time, high-to-low-level output from A input	$C_L = 15 \text{ pF}, R_L = 4 \text{ k}\Omega,$		100	ns
tplH Propagation delay time, low-to-high-level output from A input	See Note 3		100	115
tpHL Propagation delay time, high-to-low-level output (a-f only) from RBI input	$C_L = 15 \text{ pF}, R_L = 6 \text{ k}\Omega,$		100	ns
tPLH Propagation delay time, low-to-high-level output (a-f only) from RBI input	See Note 3		100	

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



 $[\]ddagger$ All typical values are at $V_{CC} = 5 \text{ V}$, $T_A 25^{\circ}$ C.

NOTE 2: I_{CC} is measured with all outputs open and all inputs at 4.5 V.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)														7 V
Input voltage														7 V
Current forced into any output in the off state														1 mA
Operating free-air temperature range: SN54LS49											5	55°(C to	125°C
SN74LS49												U	Ct	0 /U C
Storage temperature range				 -				-	-		-6	5°(: to	150°C

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

	S	N54LS	19	S	N74LS	19	UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	Uiti
Supply voltage, V _{CC}	4.5	5	5.5	4.75	5	5.25	V
High-level output voltage, VOH			5.5			5.5	V
Low-level output current, IOL			4			В	mA
Operating free-air temperature, TA	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST COA	NDITIONS†	S	N54LS4	19	S	N74LS4	19	
	TANAMETER	TEST CON	ADITIONS,	MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNIT
VIH	High-level input voltage			2			2			V
VIL	Low-level input voltage					0.7			0.8	V
VIK	Input clamp voltage	VCC = MIN,	I _I = -18 mA			-1.5			-1.5	V
ІОН	High-level output current	V _{CC} = MIN, V _{IL} = V _{IL} max,	V _{IH} = 2 V, V _{OH} = 5.5 V			250			250	μА
VOL	Low-level output voltage	V _{CC} = MIN, V _{IH} = 2 V,	IOL = 4 mA		0.25	0.4		0.25	0.4	V
		VIL = VIL max	1 _{OL} = 8 mA					0.35	0.5	
Ц	Input current at maximum input voltage	V _{CC} = MAX,	V ₁ = 7 V			0.1			0.1	mA
IН	High-level input current	V _{CC} = MAX,	V _I = 2.7 V			20			20	μΑ
IIL	Low-level input current	V _{CC} = MAX,	V ₁ = 0.4 V			-0.4			-0.4	mA
lcc	Supply current	V _{CC} = MAX,	See Note 2		8	15		8	15	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics, VCC = 5 V, TA = 25°C

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
tPHL	Propagation delay time, high-to-low-level output from A input	$C_L = 15 \text{ pF}, R_L = 4 \text{ k}\Omega,$			100	
^t PLH	Propagation delay time, low-to-high-level output from A input	See Note 3		·	100	ns
tPHL	Propagation delay time, high-to-low-level output (a-f only) from RBI input	$C_L = 15 \text{ pF}, R_L = 6 \text{ k}\Omega,$			100	
tPLH	Propagation delay time, low-to-high-level output (a-f only) from $\overline{\text{RBI}}$ input	See Note 3			100	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



 $[\]ddagger$ All typical values are at V_{CC} = 5 V, T_A = 25°C. NOTE 2: I_{CC} is measured with all outputs open and all inputs at 4.5 V.





25-Oct-2016

PACKAGING INFORMATION

Orderable Device	Status	Package Type	_	Pins	_	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
5962-9856401QEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9856401QE A SNJ5447AJ	Samples
962-9856401QFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9856401QF A SNJ5447AW	Samples
7604501EA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7604501EA SNJ54LS47J	Samples
7604501FA	OBSOLETI	E		16		TBD	Call TI	Call TI	-55 to 125		
SN5447AJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN5447AJ	Samples
SN54LS47J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS47J	Samples
SN54LS49J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS49J	Samples
SN7446AN	OBSOLETI	E PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN7447AN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN7447AN	Samples
SN7447AN3	OBSOLETI	E PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN7447ANE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN7447AN	Samples
SN7448N	OBSOLETI	E PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74LS47D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS47	Samples
SN74LS47DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS47	Samples
SN74LS47DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		LS47	Samples
SN74LS47N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS47N	Samples
SN74LS47N3	OBSOLETI	E PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74LS47NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS47N	Samples
SN74LS47NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS47	Samples



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PACKAGE OPTION ADDENDUM

25-Oct-2016

Orderable Device	Status	Package Type	Package	Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
SN74LS48N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SNJ5447AJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9856401QE A SNJ5447AJ	Samples
SNJ5447AW	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9856401QF A SNJ5447AW	Samples
SNJ54LS47FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54LS 47FK	Samples
SNJ54LS47J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7604501EA SNJ54LS47J	Samples
SNJ54LS47W	OBSOLETE			16		TBD	Call TI	Call TI	-55 to 125		
SNJ54LS49J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS49J	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.



PACKAGE OPTION ADDENDUM

25-Oct-2016

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN5446A, SN5447A, SN5448, SN54LS47, SN54LS49, SN54LS49, SN7446A, SN7447A, SN74LS47, SN74LS48, SN74LS49:

• Catalog: SN7446A, SN7447A, SN7448, SN74LS47, SN74LS48, SN74LS49

Military: SN5446A, SN5447A, SN5448, SN54LS47, SN54LS48, SN54LS49

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS47DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
SN74LS47DR	SOIC	D	16	2500	333.2	345.9	28.6	

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



D (R-PDS0-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP2-F16



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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